

Title (en)

METHOD AND ADHESIVE APPLICATOR FOR THE CONTACTLESS APPLICATION OF A MULTIPLICITY OF DISCRETE SPOTS OF ADHESIVE, DISTRIBUTED OVER A SURFACE AREA, PERMANENTLY TO A SUBSTRATE

Title (de)

VERFAHREN UND KLEBSTOFFAUFTRAGSVORRICHTUNG ZUM BERÜHRUNGSFREIEN AUFTRAGEN EINER VIELZAHL VON AUF EINE FLÄCHE VERTEILTEN, NICHT ZUSAMMENHÄNGENDEN KLEBSTOFFPUNKTEN AUF EIN SUBSTRAT ZUM DAUERHAFTEN VERBLEIB

Title (fr)

PROCÉDÉ ET DISPOSITIF D'APPLICATION DE SUBSTANCE ADHÉSIVE POUR APPLIQUER SANS CONTACT PLUSIEURS POINTS DE SUBSTANCE ADHÉSIVE SÉPARÉS RÉPARTIS SUR UNE SURFACE, DE MANIÈRE PERMANENTE SUR UN SUBSTRAT

Publication

**EP 2613891 B1 20150325 (DE)**

Application

**EP 11770043 A 20110907**

Priority

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- EP 2011004502 W 20110907

Abstract (en)

[origin: WO2012031750A1] In a method for applying a multiplicity of discrete spots of adhesive, distributed over a surface area, permanently to a substrate (3), reduced formation of threads of adhesive is achieved by a rotating applicator head that bears a pattern of openings around its circumference being moved in a direction of application (11) at a lateral distance from and in relation to the surface of the substrate that is to be permanently provided with the pattern, the adhesive is forced out of the openings (2) in the applicator head in the region of a linear or strip-like spacing gap (G) formed between the substrate and the applicator head to form lenticular blobs (4B), the blobs of adhesive are brought into contact with the substrate in the region of the spacing gap, without the applicator head thereby touching the substrate, and the blobs of adhesive are pulled away from the respective openings while becoming attached to the substrate and forming spots of adhesive (4) on the substrate.

IPC 8 full level

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CPC (source: EP US)

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